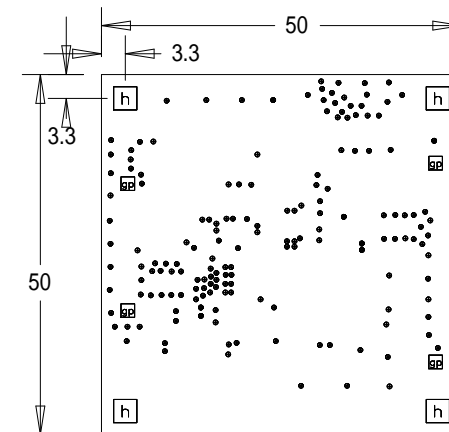
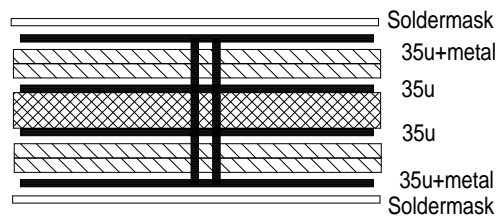


SPEC:


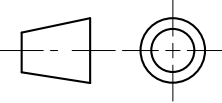
COMPLIANT RoHS DIRECTIVE 2011/65/EU

MATERIAL	FR4 HTG180 (low CTE)
BOARD THICKNESS	1.0mm /39mils
STACKUP	MC4 /4LAYERS
MINIMAL GAP	200um /7.8mils
MINIMAL SLIVER	200um /7.8mils
COPPER THICKNESS	35um(1oz) at start
FINISH THICKNESS	CHEMICAL NiAu 0.05um(0.002mils)GOLD/ OVER 5um(0.2mils) NICKEL
SOLDER MASK	White TOP & BOT
SILKSCREEN	Black TOP
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON TOP SILKSCREEN	



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
•	0.3 VIA	PLATED	174
h	3.2	PLATED	4
h	1.9	NON-PLATED	4

All 0.3mm Via must be plugged and capped

1.0	W32/2020	
indice	Description	Date
Controle par :		Autorise par:
 ON semiconductor		Definition CUT & DRILL DRAWING PLAN PERCAGE DETOURAGE 
		Subc. DYPE TECH Dessine: e B Echelle: 1/1
Board: SCV78514 LMD		Pages: 1/3
CE DOCUMENT EST LA PROPRIETE DE ON semiconductor IL NE PEUT ETRE UTILISER, REPRODUIT OU COMMUNIQUER SANS SONT AUTHORIZATION		Format: A3
THIS DOCUMENT IS ON semiconductor PROPERTY, IT MAY NOT BE USED, REPRODUCED OR TRANSMITTED WITHOUT THEIR APPROVAL.		